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Qualification and performance specification of permanent solder mask and flexible cover materials

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

QUALIFICATION AND PERFORMANCE SPECIFICATION OF PERMANENT SOLDER MASK AND FLEXIBLE COVER MATERIALS

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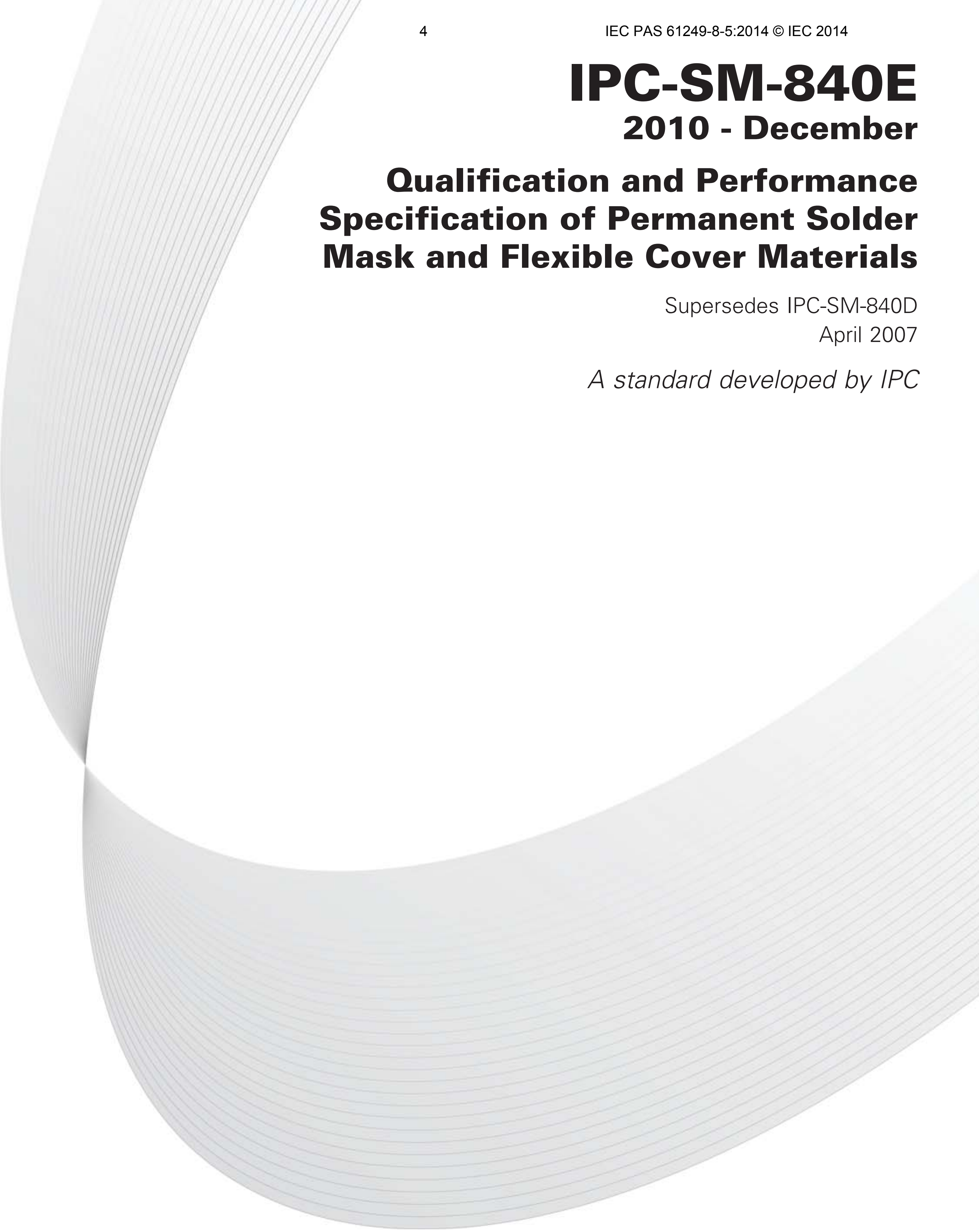

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2010 - December

Qualification and Performance Specification of Permanent Solder Mask and Flexible Cover Materials

Supersedes IPC-SM-840D
April 2007

A standard developed by IPC

Association Connecting Electronics Industries

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IPC-SM-840E

Qualification and Performance Specification of Permanent Solder Mask and Flexible Cover Materials

Developed by the Solder Mask Performance Task Group (5-33B) of the Cleaning and Coating Committee (5-30) and the Covercoat Materials Task Group (D-13B) of the Flexible Circuits Committee (D-10) of IPC

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Users of this publication are encouraged to participate in the development of future revisions.

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Qualification and Performance Specification of Permanent Solder Mask and Flexible Cover Materials

1 SCOPE AND DESIGNATION

1.1 Scope This specification **shall** define the criteria for and method of obtaining the maximum information about and confidence in cured permanent solder mask and cover material under evaluation with the minimum of test redundancy.

This specification **shall** establish the requirements for:

- The evaluation of solder mask and cover materials
- The conformance of solder mask and cover material properties
- The qualification of the solder mask and cover material via the appropriate test substrate
- The qualification assessment of the solder mask and cover material in conjunction with the production printed board process